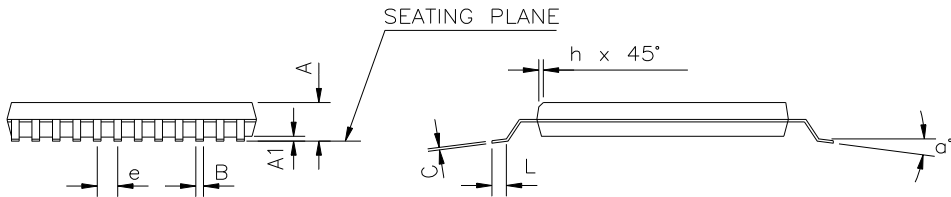
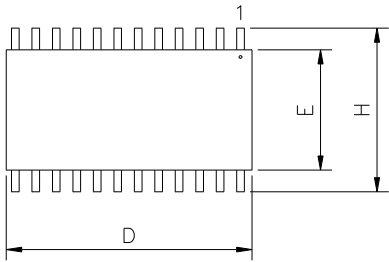


150 MIL TQSOP
THIN QUARTER SIZE OUTLINE PACKAGE (TQSOP)

PACKAGE INFORMATION

NOTES

- 1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
- 2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
- 3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
- 4. DIMENSIONS ARE GIVEN IN INCHES.
- 5. LEAD COPLANARITY IS 0.003 INCH MAX.



JEDEC #	—		—	
TYPE	20	LEAD	24	LEAD
SYMBOL	Min	Max	Min	Max
A	0.040	0.048	0.040	0.048
A1	0.002	0.006	0.002	0.006
B	0.009	0.012	0.009	0.012
C	0.007	0.010	0.007	0.010
D	0.337	0.344	0.337	0.344
E	0.150	0.157	0.150	0.157
e	0.025 BSC		0.025 BSC	
H	0.228	0.244	0.228	0.244
h	0.010	0.016	0.010	0.016
L	0.016	0.035	0.016	0.035
α°	0°	8°	0°	8°

PREPARED BY	NK	REF. NO.	REV. NO.	SPEL SEMICONDUCTOR LIMITED INDIA	
CHECKED BY	SP	DIM-QSOP-02	1		
APPROVED BY	NJC		DATE 01.07.01		